

## TGP3000E Thermal Gap Filler Pad

### BENEFITS AND FEATURES

- High thermal performance
- Ultra-high compressibility for low stress applications
- Excellent surface wetting for low contact resistance
- High reliability
- Electrically insulating

### OVERVIEW

Honeywell TGP3000E Thermal Gap Filler Pads provide high thermal performance with ease of use across multitude of applications. Its ultra-high compressibility enables low stress and excellent conformity to mating surfaces. It is designed to minimize thermal resistance at interfaces, and maintain excellent performance through reliability testing. TGP3000E naturally tacky, and require no additional adhesive which could inhibit thermal performance. Products are available in thickness range from 0.5mm to 5.0mm.

### TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications & network servers
- Automotive electronics
- Power devices & modules
- Semiconductor logics & memory

### STORAGE & USE

- Shelf life 12 months at 0-35°C,  
≤65% RH

Property	TGP3000E	Test Method
Color	Green	Visual
Thickness (mm) 1*	0.5-5.0	ASTM D374
Density(g/cm <sup>3</sup> )	2.9	ASTM D792
Hardness (Shore00)	50	ASTM D2240
Thermal Conductivity (W/m·K)	3.0	ASTM D5470
Thermal Impedance (°C·in <sup>2</sup> /W) (1mm@10psi, Typical Value)	0.50	ASTM D5470
Dielectric Constant@1MHz	5.5	ASTM D150
Volume Resistivity (ohm-cm)	1.0 x 10 <sup>14</sup>	ASTM D257
Dielectric Strength (KV/mm)	≥10	ASTM D149
Flammability Rating	V-0	UL 94
Operating Temperature (°C)	-40-200	HON Internal

1\* Thickness range: 0.5-5.0mm with 0.25mm incremental

Thickness Tolerance: ≥1.0mm, ±10%

0.5-1.0mm, ±0.1mm

\*Typical property data values should not be used as specifications

### Honeywell Electronic Materials

USA: 1-509-252-2102

China: 400-840-2233

Germany: 49-5137-999-9199

Japan: 81-3-6730-7092

Korea: 82-2-3483-5076

Singapore: 65-6580-3593

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